

KetaSpire® MS NT1 AM Filament polyetheretherketone

Ketaspire® MS NT1 AM Filament provides long-term performance up to 240 °C, including exceptional chemical resistance, outstanding wear and abrasion resistance. These properties make it

particularly suited for metal replacement in critical applications in severe end-use environments, such as Oil & Gas, Aerospace and Automotive.

General

Material Status	 Commercial: Active 		
Availability	 Africa & Middle East Asia Pacific Europe	Latin AmericaNorth America	ı
Features	Chemical ResistantDuctileFlame Retardant	Good Dimensional StabilityGood Impact ResistanceHigh Heat Resistance	
Uses	Aerospace ApplicationsAutomotive Applications	Oil/Gas Applications	
RoHS Compliance	 Contact Manufacturer 		
Appearance	 Natural Color 		
Forms	• Filament		
Processing Method	3D Printing, Fused Filament Fabrication (FFF)		
Physical	Typical Value Unit		Test method
Density / Specific Gravity		1.29	ASTM D792
Mechanical	Турі	cal Value Unit	Test method
Tensile Modulus		3120 MPa	ASTM D638
Tensile Strength			ASTM D638
Yield		85.0 MPa	
Break		48.0 MPa	
Tensile Elongation			ASTM D638
Yield		4.8 %	
Break		26 %	
Impact	Турі	cal Value Unit	Test method
Notched Izod Impact		81 J/m	ASTM D256
Thermal	Турі	cal Value Unit	Test method
Melting Temperature	/1	343 °C	ASTM D3418
Additional Information	iavT	cal Value Unit	
Diameter - Filament	/-	1.75 mm	

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polyetheretherketone

Printing conditions for above data table:

• Filament drying conditions, minimum 4h: 150°C

• Extruder temperature: 400-440°C

• Bed temperature: 180-220°C

· Printing tool path: cross hatching in the XY plane

Test specimen parameters:

• First layer: 0.3mm thick

Subsequent layers: 0.1mm

100% infill3 shells

• Printing speed: 18 mm/s

Notes

Typical properties: these are not to be construed as specifications.

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Safety Data Sheets (SDS) are available by emailing us or contacting your sales representative. Always consult the appropriate SDS before using any of our products.

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